

Title (en)
HIGH-IMPACT POLYSTYRENE RESIN COMPOSITION

Title (de)
SCHLAGFESTE POLYSTYROLHARZZUSAMMENSETZUNG

Title (fr)
COMPOSITION DE RESINE DE POLYSTYRENE EXTREMEMENT RESISTANTE AUX CHOCS

Publication
EP 0733675 A4 19980204 (EN)

Application
EP 95933611 A 19951004

Priority
• JP 9502029 W 19951004
• JP 24097294 A 19941005

Abstract (en)
[origin: EP0733675A1] The present invention relates to an impact resistant polystyrene composition which comprises 5 to 97% by weight of an (a) styrenic polymer having syndiotactic configuration, 2 to 95% by weight of a (b) rubbery elastomer having an olefinic component or a polyolefin, and 0.5 to 10% by weight of a (c) styrene/olefin block or graft copolymer having a micro-phase separation temperature of 180 DEG C at the highest when diluted with dioctyl phthalate to a solution with a concentration of 60% by weight. According to the present invention, an impact resistant polystyrene composition can be provided which is greatly enhanced in impact resistance and extensibility without impairing heat resistance and modulus of elasticity.

IPC 1-7
C08L 25/00; **C08L 21/00**; **C08L 23/00**; **C08K 3/00**; **C08L 71/12**; **C08L 53/02**; **C08L 51/00**

IPC 8 full level
C08L 23/00 (2006.01); **C08L 21/00** (2006.01); **C08L 23/02** (2006.01); **C08L 23/16** (2006.01); **C08L 25/00** (2006.01); **C08L 25/04** (2006.01); **C08L 25/06** (2006.01); **C08L 53/02** (2006.01)

CPC (source: EP US)
C08L 21/00 (2013.01 - EP US); **C08L 23/02** (2013.01 - EP US); **C08L 23/16** (2013.01 - EP US); **C08L 25/06** (2013.01 - EP US); **C08L 53/02** (2013.01 - EP US)

Citation (search report)
• [X] EP 0318793 A1 19890607 - IDEMITSU KOSAN CO [JP]
• [X] EP 0324398 A1 19890719 - IDEMITSU KOSAN CO [JP]
• See references of WO 9611233A1

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Designated contracting state (EPC)
DE FR GB IT NL

DOCDB simple family (publication)
EP 0733675 A1 19960925; **EP 0733675 A4 19980204**; **EP 0733675 B1 20020227**; DE 69525610 D1 20020404; DE 69525610 T2 20020814; JP H08104785 A 19960423; US 5777028 A 19980707; US 6048932 A 20000411; WO 9611233 A1 19960418

DOCDB simple family (application)
EP 95933611 A 19951004; DE 69525610 T 19951004; JP 24097294 A 19941005; JP 9502029 W 19951004; US 64801796 A 19960531; US 7269498 A 19980506